Microchip Technology - DSPIC33FJ06GS001-I/SS Datasheet

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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	dsPIC
Core Size	16-Bit
Speed	40 MIPs
Connectivity	I²C, IrDA, LINbus, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	13
Program Memory Size	6KB (2K x 24)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	256 x 8
Voltage - Supply (Vcc/Vdd)	3V ~ 3.6V
Data Converters	A/D 6x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	20-SSOP (0.209", 5.30mm Width)
Supplier Device Package	20-SSOP
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/dspic33fj06gs001-i-ss

REGISTER 3-1: SR: CPU STATUS REGISTER (CONTINUED)

bit 7-5 **IPL<2:0>:** CPU Interrupt Priority Level Status bits(2,3)
111 = CPU Interrupt Priority Level is 7 (15), user interrupts disabled
110 = CPU Interrupt Priority Level is 6 (14)
101 = CPU Interrupt Priority Level is 5 (13)
100 = CPU Interrupt Priority Level is 4 (12)
011 = CPU Interrupt Priority Level is 3 (11)
010 = CPU Interrupt Priority Level is 2 (10)
001 = CPU Interrupt Priority Level is 1 (9)
000 = CPU Interrupt Priority Level is 0 (8)

bit 4 **RA:** REPEAT Loop Active bit
1 = REPEAT loop in progress
0 = REPEAT loop not in progress

bit 3 **N:** MCU ALU Negative bit
1 = Result was negative
0 = Result was non-negative (zero or positive)

bit 2 **OV:** MCU ALU Overflow bit
This bit is used for signed arithmetic (2's complement). It indicates an overflow of a magnitude that causes the sign bit to change state.
1 = Overflow occurred for signed arithmetic (in this arithmetic operation)
0 = No overflow occurred

bit 1 **Z:** MCU ALU Zero bit
1 = An operation that affects the Z bit has set it at some time in the past
0 = The most recent operation that affects the Z bit has cleared it (i.e., a non-zero result)

bit 0 **C:** MCU ALU Carry/$\overline{\text{Borrow}}$ bit
1 = A carry-out from the Most Significant bit of the result occurred
0 = No carry-out from the Most Significant bit of the result occurred

Note 1: This bit can be read or cleared (not set).

2: The IPL<2:0> bits are concatenated with the IPL3 bit (CORCON<3>) to form the CPU Interrupt Priority Level (IPL). The value in parentheses indicates the IPL if IPL3 = 1. User interrupts are disabled when IPL3 = 1.

3: The IPL<2:0> Status bits are read-only when NSTDIS = 1 (INTCON1<15>).

4: Clearing this bit will clear SA and SB.

TABLE 4-12: HIGH-SPEED PWM REGISTER MAP

File Name	Addr Offset	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
PTCON	0400	PTEN	—	PTSIDL	SESTAT	SEIEN	EIPU	SYNCPOL	SYNCOEN	SYNCEN	—	SYNCSRC<1:0>		SEVTPS<3:0>				0000
PTCON2	0402	—	—	—	—	—	—	—	—	—	—	—	—	—	PCLKDIV<2:0>			0000
PTPER	0404	PTPER<15:0>																FFF8
SEVTCMP	0406	SEVTCMP<15:3>													—	—	—	0000
MDC	040A	MDC<15:0>																0000
CHOP	041A	CHPCLKEN	—	—	—	—	—	CHOPCLK<6:0>							—	—	—	0000

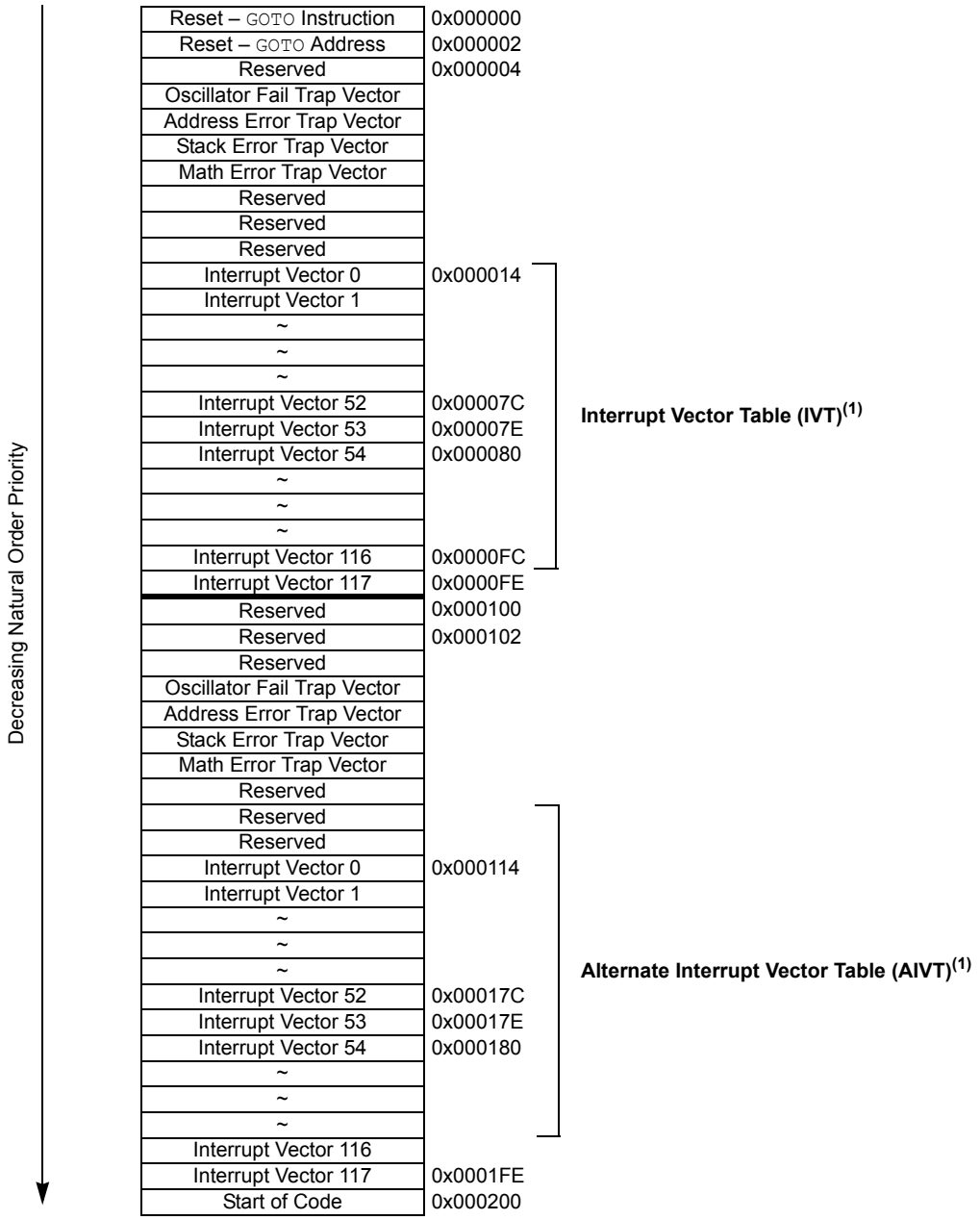
Legend: x = unknown value on Reset, — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

TABLE 4-13: HIGH-SPEED PWM GENERATOR 1 REGISTER MAP

File Name	Addr Offset	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
PWMCON1	0420	FLTSTAT	CLSTAT	TRGSTAT	FLTIEN	CLIEN	TRGIEN	ITB	MDCS	DTC<1:0>		—	—	—	CAM	XPRES	IUE	0000
IOCON1	0422	PENH	PENL	POLH	POLL	PMOD<1:0>		OVRENH	OVRENL	OVRDAT<1:0>		FLTDAT<1:0>		CLDAT<1:0>		SWAP	OSYNC	0000
FCLCON1	0424	IFLTMOD	CLSRC<4:0>					CLPOL	CLMOD	FLTSRC<4:0>					FLTPOL	FLTMOD<1:0>		0000
PDC1	0426	PDC1<15:0>																0000
PHASE1	0428	PHASE1<15:0>																0000
DTR1	042A	—	—	DTR1<13:0>														0000
ALTDTR1	042C	—	—	ALTDTR1<13:0>														0000
SDC1	042E	SDC1<15:0>																0000
SPHASE1	0430	SPHASE1<15:0>																0000
TRIG1	0432	TRGCMP<15:3>													—	—	—	0000
TRGCON1	0434	TRGDIV<3:0>				—	—	—	—	DTM	—	TRGSTRT<5:0>						0000
STRIG1	0436	STRGCMP<15:3>													—	—	—	0000
PWMCAP1	0438	PWMCAP1<15:3>													—	—	—	0000
LEBCON1	043A	PHR	PHF	PLR	PLF	FLTLEBEN	CLLEBEN	LEB<6:0>							—	—	—	0000
AUXCON1	043E	HRPDIS	HRDDIS	—	—	—	—	—	—	—	—	CHOPSEL<3:0>				CHOPHEN	CHOPLEN	0000

Legend: x = unknown value on Reset, — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

FIGURE 7-1: dsPIC33FJ06GS001/101A/102A/202A and dsPIC33FJ09GS302 INTERRUPT VECTOR TABLE



Note 1: See Table 7-1 for the list of implemented interrupt vectors.

REGISTER 7-26: IPC14: INTERRUPT PRIORITY CONTROL REGISTER 14

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 15							bit 8

U-0	R/W-1	R/W-0	R/W-0	U-0	U-0	U-0	U-0
—	PSEMIP<2:0>			—	—	—	—
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-7 **Unimplemented:** Read as '0'

bit 6-4 **PSEMIP<2:0>:** PWM Special Event Match Interrupt Priority bits
111 = Interrupt is Priority 7 (highest priority interrupt)
•
•
•
001 = Interrupt is Priority 1
000 = Interrupt source is disabled

bit 3-0 **Unimplemented:** Read as '0'

REGISTER 7-27: IPC16: INTERRUPT PRIORITY CONTROL REGISTER 16

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 15							bit 8

U-0	R/W-1	R/W-0	R/W-0	U-0	U-0	U-0	U-0
—	U1EIP<2:0>(1)			—	—	—	—
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-7 **Unimplemented:** Read as '0'

bit 6-4 **U1EIP<2:0>:** UART1 Error Interrupt Priority bits(1)
111 = Interrupt is Priority 7 (highest priority interrupt)
•
•
•
001 = Interrupt is Priority 1
000 = Interrupt source is disabled

bit 3-0 **Unimplemented:** Read as '0'

Note 1: These bits are not implemented in the dsPIC33FJ06GS001 device.

REGISTER 8-1: OSCCON: OSCILLATOR CONTROL REGISTER(1,3) (CONTINUED)

bit 4 **Unimplemented:** Read as '0'

bit 3 **CF:** Clock Fail Detect bit (read/clear by application)
1 = FSCM has detected clock failure
0 = FSCM has not detected clock failure

bit 2-1 **Unimplemented:** Read as '0'

bit 0 **OSWEN:** Oscillator Switch Enable bit
1 = Request oscillator switch to selection specified by NOSC<2:0> bits
0 = Oscillator switch is complete

Note 1: Writes to this register require an unlock sequence. Refer to **Section 42. "Oscillator (Part IV)"** (DS70307) in the *"dsPIC33F/PIC24H Family Reference Manual"* for details.

2: Direct clock switches between any Primary Oscillator mode with PLL and FRCPLL mode are not permitted. This applies to clock switches in either direction. In these instances, the application must switch to FRC mode as a transition clock source between the two PLL modes.

3: This register is reset only on a Power-on Reset (POR).

8.5 Clock Switching Operation

Applications are free to switch among any of the four clock sources (primary, LP, FRC and LPRC) under software control at any time. To limit the possible side effects of this flexibility, devices have a safeguard lock built into the switch process.

Note: Primary Oscillator mode has three different submodes (XT, HS and EC), which are determined by the POSCMD<1:0> Configuration bits. While an application can switch to and from Primary Oscillator mode in software, it cannot switch among the different primary submodes without reprogramming the device.

8.5.1 ENABLING CLOCK SWITCHING

To enable clock switching, the FCKSM1 Configuration bit in the FOSC Configuration register must be programmed to '0'. (Refer to **Section 22.1 "Configuration Bits"** for further details.) If the FCKSM1 Configuration bit is unprogrammed ('1'), the clock switching function and Fail-Safe Clock Monitor function are disabled. This is the default setting.

The NOSC<2:0> control bits (OSCCON<10:8>) do not control the clock selection when clock switching is disabled. However, the COSC<2:0> bits (OSCCON<14:12>) reflect the clock source selected by the FNOSC Configuration bits.

The OSWEN control bit (OSCCON<0>) has no effect when clock switching is disabled. It is held at '0' at all times.

8.5.2 OSCILLATOR SWITCHING SEQUENCE

To perform a clock switch, the following basic sequence is required:

1. If desired, read the COSC<2:0> bits to determine the current oscillator source.
2. Perform the unlock sequence to allow a write to the OSCCON register high byte.
3. Write the appropriate value to the NOSC<2:0> control bits for the new oscillator source.
4. Perform the unlock sequence to allow a write to the OSCCON register low byte.
5. Set the OSWEN bit (OSCCON<0>) to initiate the oscillator switch.

Once the basic sequence is completed, the system clock hardware responds automatically as follows:

1. The clock switching hardware compares the COSC<2:0> status bits with the new value of the NOSC<2:0> control bits. If they are the same, the clock switch is a redundant operation. In this case, the OSWEN bit is cleared automatically and the clock switch is aborted.
2. If a valid clock switch has been initiated, the LOCK (OSCCON<5>) and the CF (OSCCON<3>) status bits are cleared.
3. The new oscillator is turned on by the hardware if it is not currently running. If a crystal oscillator must be turned on, the hardware waits until the Oscillator Start-up Timer (OST) expires. If the new source is using the PLL, the hardware waits until a PLL lock is detected (LOCK = 1).
4. The hardware waits for 10 clock cycles from the new clock source and then performs the clock switch.
5. The hardware clears the OSWEN bit to indicate a successful clock transition. In addition, the NOSC<2:0> bit values are transferred to the COSC<2:0> status bits.
6. The old clock source is turned off at this time, with the exception of LPRC (if WDT or FSCM is enabled).

Note 1: The processor continues to execute code throughout the clock switching sequence. Timing-sensitive code should not be executed during this time.

2: Direct clock switches between any Primary Oscillator mode with PLL and FRCPLL mode are not permitted. This applies to clock switches in either direction. In these instances, the application must switch to FRC mode as a transition clock source between the two PLL modes.

3: Refer to **Section 42. "Oscillator (Part IV)"** (DS70307) in the *"dsPIC33F/PIC24H Family Reference Manual"* for details.

13.1 Input Capture Registers

REGISTER 13-1: IC1CON: INPUT CAPTURE 1 CONTROL REGISTER

U-0	U-0	R/W-0	U-0	U-0	U-0	U-0	U-0
—	—	ICSIDL	—	—	—	—	—
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R-0, HC	R-0, HC	R/W-0	R/W-0	R/W-0
ICTMR(1)	ICI<1:0>		ICOV	ICBNE	ICM<2:0>		
bit 7							bit 0

Legend:	HC = Hardware Clearable bit		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-14 **Unimplemented:** Read as '0'

bit 13 **ICSIDL:** Input Capture Module Stop in Idle Control bit
1 = Input capture module halts in CPU Idle mode
0 = Input capture module continues to operate in CPU Idle mode

bit 12-8 **Unimplemented:** Read as '0'

bit 7 **ICTMR:** Input Capture Timer Select bit(1)
1 = TMR2 contents are captured on capture event
0 = Reserved

bit 6-5 **ICI<1:0>:** Select Number of Captures per Interrupt bits
11 = Interrupt on every fourth capture event
10 = Interrupt on every third capture event
01 = Interrupt on every second capture event
00 = Interrupt on every capture event

bit 4 **ICOV:** Input Capture Overflow Status Flag bit (read-only)
1 = Input capture overflow occurred
0 = No input capture overflow occurred

bit 3 **ICBNE:** Input Capture Buffer Empty Status bit (read-only)
1 = Input capture buffer is not empty, at least one more capture value can be read
0 = Input capture buffer is empty

bit 2-0 **ICM<2:0>:** Input Capture Mode Select bits
111 = Input capture functions as interrupt pin only when device is in Sleep or Idle mode. Rising edge detect only; all other control bits are not applicable.
110 = Unused (module disabled)
101 = Capture mode, every 16th rising edge
100 = Capture mode, every 4th rising edge
011 = Capture mode, every rising edge
010 = Capture mode, every falling edge
001 = Capture mode, every edge (rising and falling). ICI<1:0> bits do not control interrupt generation for this mode.
000 = Input capture module is turned off

Note 1: This bit is not available in dsPIC33FJ06GS001/101A/102A devices.

14.1 Output Compare Modes

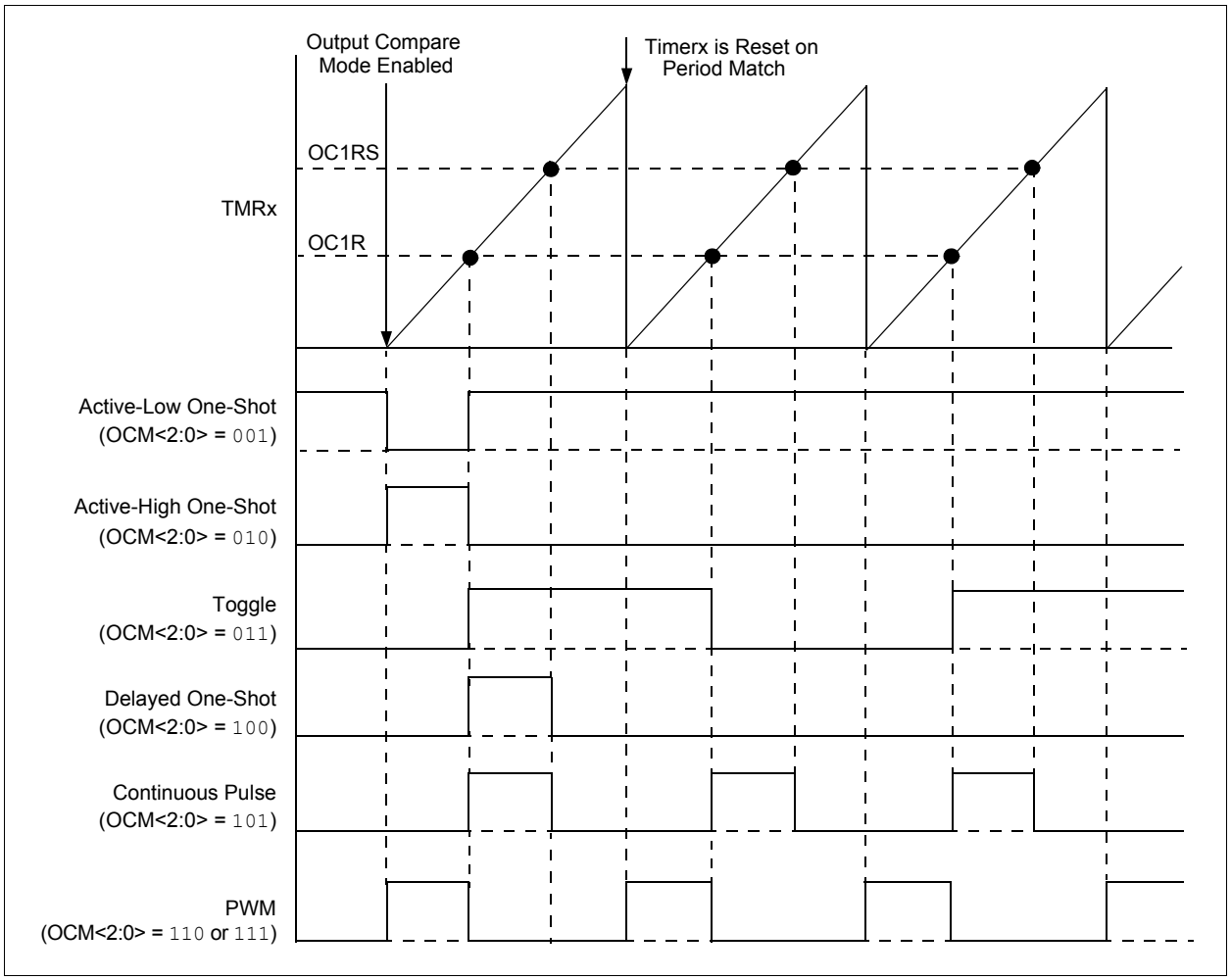
Configure the Output Compare modes by setting the appropriate Output Compare Mode (OCM<2:0>) bits in the Output Compare Control (OC1CON<2:0>) register. Table 14-1 lists the different bit settings for the Output Compare modes. Figure 14-2 illustrates the output compare operation for various modes. The user application must disable the associated timer when writing to the Output Compare Control registers to avoid malfunctions.

Note:	Refer to **Section 13. "Output Compare"** (DS70209) in the *"dsPIC33F/PIC24H Family Reference Manual"* for OC1R and OC1RS register restrictions.

TABLE 14-1: OUTPUT COMPARE MODES

OCM<2:0>	Mode	OC1 Pin Initial State	OC1 Interrupt Generation
000	Module Disabled	Controlled by GPIO register	—
001	Active-Low One-Shot	0	OC1 rising edge
010	Active-High One-Shot	1	OC1 falling edge
011	Toggle	Current output is maintained	OC1 rising and falling edge
100	Delayed One-Shot	0	OC1 falling edge
101	Continuous Pulse	0	OC1 falling edge
110	PWM without Fault Protection	'0' if OC1R is zero, '1' if OC1R is non-zero	No interrupt
111	PWM with Fault Protection	'0' if OC1R is zero, '1' if OC1R is non-zero	OCFA falling edge for OC1 to OC4

FIGURE 14-2: OUTPUT COMPARE OPERATION



NOTES:

REGISTER 18-2: U1STA: UART1 STATUS AND CONTROL REGISTER (CONTINUED)

bit 7-6 **URXISEL<1:0>:** Receive Interrupt Mode Selection bits(2)

11 = Interrupt is set on U1RSR transfer, making the receive buffer full (i.e., has 4 data characters)
10 = Interrupt is set on U1RSR transfer, making the receive buffer 3/4 full (i.e., has 3 data characters)
0x = Interrupt is set when any character is received and transferred from the U1RSR to the receive buffer; receive buffer has one or more characters

bit 5 **ADDEN:** Address Character Detect bit (bit 8 of received data = 1)(2)

1 = Address Detect mode is enabled; if 9-bit mode is not selected, this does not take effect
0 = Address Detect mode is disabled

bit 4 **RIDLE:** Receiver Idle bit (read-only)(2)

1 = Receiver is Idle
0 = Receiver is active

bit 3 **PERR:** Parity Error Status bit (read-only)(2)

1 = Parity error has been detected for the current character (character at the top of the receive FIFO)
0 = Parity error has not been detected

bit 2 **FERR:** Framing Error Status bit (read-only)(2)

1 = Framing error has been detected for the current character (character at the top of the receive FIFO)
0 = Framing error has not been detected

bit 1 **OERR:** Receive Buffer Overrun Error Status bit (clear/read-only)(2)

1 = Receive buffer has overflowed
0 = Receive buffer has not overflowed. Clearing a previously set OERR bit (1 → 0 transition) will reset the receiver buffer and the U1RSR to the empty state.

bit 0 **URXDA:** Receive Buffer Data Available bit (read-only)(2)

1 = Receive buffer has data, at least one more character can be read
0 = Receive buffer is empty

Note 1: Refer to **Section 17. "UART"** (DS70188) in the *"dsPIC33F/PIC24H Family Reference Manual"* for information on enabling the UART module for transmit operation.

2: This bit is not available in the dsPIC33FJ06GS001 device.

TABLE 23-2: INSTRUCTION SET OVERVIEW (CONTINUED)

Base Instr #	Assembly Mnemonic	Assembly Syntax	Description	# of Words	# of Cycles	Status Flags Affected
10	BTSC	BTSC f,#bit4	Bit Test f, Skip if Clear	1	1 (2 or 3)	None
		BTSC Ws,#bit4	Bit Test Ws, Skip if Clear	1	1 (2 or 3)	None
11	BTSS	BTSS f,#bit4	Bit Test f, Skip if Set	1	1 (2 or 3)	None
		BTSS Ws,#bit4	Bit Test Ws, Skip if Set	1	1 (2 or 3)	None
12	BTST	BTST f,#bit4	Bit Test f	1	1	Z
		BTST.C Ws,#bit4	Bit Test Ws to C	1	1	C
		BTST.Z Ws,#bit4	Bit Test Ws to Z	1	1	Z
		BTST.C Ws,Wb	Bit Test Ws<Wb> to C	1	1	C
		BTST.Z Ws,Wb	Bit Test Ws<Wb> to Z	1	1	Z
13	BTSTS	BTSTS f,#bit4	Bit Test then Set f	1	1	Z
		BTSTS.C Ws,#bit4	Bit Test Ws to C, then Set	1	1	C
		BTSTS.Z Ws,#bit4	Bit Test Ws to Z, then Set	1	1	Z
14	CALL	CALL lit23	Call Subroutine	2	2	None
		CALL Wn	Call Indirect Subroutine	1	2	None
15	CLR	CLR f	f = 0x0000	1	1	None
		CLR WREG	WREG = 0x0000	1	1	None
		CLR Ws	Ws = 0x0000	1	1	None
		CLR Acc,Wx,Wxd,Wy,Wyd,AWB	Clear Accumulator	1	1	OA,OB,SA,SB
16	CLRWDT	CLRWDT	Clear Watchdog Timer	1	1	WDTO,Sleep
17	COM	COM f	$f = \overline{f}$	1	1	N,Z
		COM f,WREG	$WREG = \overline{f}$	1	1	N,Z
		COM Ws,Wd	$Wd = \overline{Ws}$	1	1	N,Z
18	CP	CP f	Compare f with WREG	1	1	C,DC,N,OV,Z
		CP Wb,#lit5	Compare Wb with lit5	1	1	C,DC,N,OV,Z
		CP Wb,Ws	Compare Wb with Ws (Wb – Ws)	1	1	C,DC,N,OV,Z
19	CP0	CP0 f	Compare f with 0x0000	1	1	C,DC,N,OV,Z
		CP0 Ws	Compare Ws with 0x0000	1	1	C,DC,N,OV,Z
20	CPB	CPB f	Compare f with WREG, with Borrow	1	1	C,DC,N,OV,Z
		CPB Wb,#lit5	Compare Wb with lit5, with Borrow	1	1	C,DC,N,OV,Z
		CPB Wb,Ws	Compare Wb with Ws, with Borrow ($Wb – Ws – \overline{C}$)	1	1	C,DC,N,OV,Z
21	CPSEQ	CPSEQ Wb, Wn	Compare Wb with Wn, Skip if =	1	1 (2 or 3)	None
22	CPSGT	CPSGT Wb, Wn	Compare Wb with Wn, Skip if >	1	1 (2 or 3)	None
23	CPSLT	CPSLT Wb, Wn	Compare Wb with Wn, Skip if <	1	1 (2 or 3)	None
24	CPSNE	CPSNE Wb, Wn	Compare Wb with Wn, Skip if ≠	1	1 (2 or 3)	None
25	DAW	DAW Wn	Wn = Decimal Adjust Wn	1	1	C
26	DEC	DEC f	f = f – 1	1	1	C,DC,N,OV,Z
		DEC f,WREG	WREG = f – 1	1	1	C,DC,N,OV,Z
		DEC Ws,Wd	Wd = Ws – 1	1	1	C,DC,N,OV,Z
27	DEC2	DEC2 f	f = f – 2	1	1	C,DC,N,OV,Z
		DEC2 f,WREG	WREG = f – 2	1	1	C,DC,N,OV,Z
		DEC2 Ws,Wd	Wd = Ws – 2	1	1	C,DC,N,OV,Z
28	DISI	DISI #lit14	Disable Interrupts for k Instruction Cycles	1	1	None

24.2 MPLAB C Compilers for Various Device Families

The MPLAB C Compiler code development systems are complete ANSI C compilers for Microchip's PIC18, PIC24 and PIC32 families of microcontrollers and the dsPIC30 and dsPIC33 families of digital signal controllers. These compilers provide powerful integration capabilities, superior code optimization and ease of use.

For easy source level debugging, the compilers provide symbol information that is optimized to the MPLAB IDE debugger.

24.3 HI-TECH C for Various Device Families

The HI-TECH C Compiler code development systems are complete ANSI C compilers for Microchip's PIC family of microcontrollers and the dsPIC family of digital signal controllers. These compilers provide powerful integration capabilities, omniscient code generation and ease of use.

For easy source level debugging, the compilers provide symbol information that is optimized to the MPLAB IDE debugger.

The compilers include a macro assembler, linker, preprocessor, and one-step driver, and can run on multiple platforms.

24.4 MPASM Assembler

The MPASM Assembler is a full-featured, universal macro assembler for PIC10/12/16/18 MCUs.

The MPASM Assembler generates relocatable object files for the MPLINK Object Linker, Intel® standard HEX files, MAP files to detail memory usage and symbol reference, absolute LST files that contain source lines and generated machine code and COFF files for debugging.

The MPASM Assembler features include:

- Integration into MPLAB IDE projects
- User-defined macros to streamline assembly code
- Conditional assembly for multipurpose source files
- Directives that allow complete control over the assembly process

24.5 MPLINK Object Linker/ MPLIB Object Librarian

The MPLINK Object Linker combines relocatable objects created by the MPASM Assembler and the MPLAB C18 C Compiler. It can link relocatable objects from precompiled libraries, using directives from a linker script.

The MPLIB Object Librarian manages the creation and modification of library files of precompiled code. When a routine from a library is called from a source file, only the modules that contain that routine will be linked in with the application. This allows large libraries to be used efficiently in many different applications.

The object linker/library features include:

- Efficient linking of single libraries instead of many smaller files
- Enhanced code maintainability by grouping related modules together
- Flexible creation of libraries with easy module listing, replacement, deletion and extraction

24.6 MPLAB Assembler, Linker and Librarian for Various Device Families

MPLAB Assembler produces relocatable machine code from symbolic assembly language for PIC24, PIC32 and dsPIC devices. MPLAB C Compiler uses the assembler to produce its object file. The assembler generates relocatable object files that can then be archived or linked with other relocatable object files and archives to create an executable file. Notable features of the assembler include:

- Support for the entire device instruction set
- Support for fixed-point and floating-point data
- Command line interface
- Rich directive set
- Flexible macro language
- MPLAB IDE compatibility

TABLE 25-10: DC CHARACTERISTICS: I/O PIN OUTPUT SPECIFICATIONS

DC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param.	**Symbol**	**Characteristic**	**Min.**	**Typ.**	**Max.**	**Units**	**Conditions**
DO10	VOL	**Output Low Voltage** I/O Pins: 4x Sink Driver Pins – RA0-RA2, RB0-RB2, RB5-RB10, RB15	—	—	0.4	V	IOL ≤ 6 mA, VDD = 3.3V**(1)**
		Output Low Voltage I/O Pins: 16x Sink Driver Pins – RA3, RA4, RB3, RB4, RB11-RB14	—	—	0.4	V	IOL ≤ 18 mA, VDD = 3.3V**(1)**
DO20	VOH	**Output High Voltage** I/O Pins: 4x Source Driver Pins – RA0-RA2, RB0-RB2, RB5-RB10, RB15	2.4	—	—	V	IOH ≥ -6 mA, VDD = 3.3V**(1)**
		Output High Voltage I/O Pins: 16x Source Driver Pins – RA3, RA4, RB3, RB4, RB11-RB14	2.4	—	—	V	IOH ≥ -18 mA, VDD = 3.3V**(1)**
DO20A	VOH1	**Output High Voltage** I/O Pins: 4x Source Driver Pins – RA0-RA2, RB0-RB2, RB5-RB10, RB15	1.5	—	—	V	IOH ≥ -12 mA, VDD = 3.3V**(1)**
			2.0	—	—		IOH ≥ -11 mA, VDD = 3.3V**(1)**
			3.0	—	—		IOH ≥ -3 mA, VDD = 3.3V**(1)**
		Output High Voltage I/O Pins: 16x Source Driver Pins – RA3, RA4, RB3, RB4, RB11-RB14	1.5	—	—	V	IOH ≥ -30 mA, VDD = 3.3V**(1)**
			2.0	—	—		IOH ≥ -25 mA, VDD = 3.3V**(1)**
			3.0	—	—		IOH ≥ -8 mA, VDD = 3.3V**(1)**

Note 1: These parameters are characterized, but not tested.

TABLE 25-11: ELECTRICAL CHARACTERISTICS: BOR

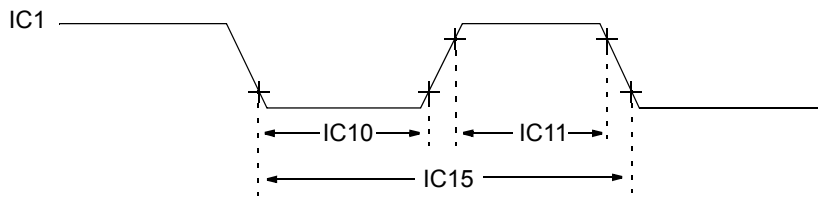
DC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V**(3)** (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param.	**Symbol**	**Characteristic**	**Min.(1)**	**Typ.**	**Max.**	**Units**	**Conditions**
BO10	VBOR	BOR Event on VDD Transition High-to-Low BOR Event is Tied to VDD Core Voltage Decrease	2.55	—	2.96	V	(See **Note 2**)

Note 1: These parameters are for design guidance only and are not tested in manufacturing.

2: The device will operate as normal until the VDDMIN threshold is reached.

3: Overall functional device operation at VBORMIN < VDD < VDDMIN is tested but not characterized. All device analog modules, such as the ADC, etc., will function but with degraded performance below VDDMIN.

FIGURE 25-6: INPUT CAPTURE (CAP1) TIMING CHARACTERISTICS



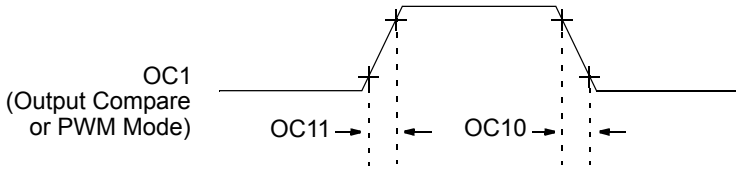
Note: Refer to Figure 25-1 for load conditions.

TABLE 25-25: INPUT CAPTURE TIMING REQUIREMENTS

AC CHARACTERISTICS				Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended			
Param.	**Symbol**	**Characteristic(1)**		**Min.**	**Max.**	**Units**	**Conditions**
IC10	TccL	IC1 Input Low Time	No prescaler	0.5 TCY + 20	—	ns	
			With prescaler	10	—	ns	
IC11	TccH	IC1 Input High Time	No prescaler	0.5 TCY + 20	—	ns	
			With prescaler	10	—	ns	
IC15	TccP	IC1 Input Period		(TCY + 40)/N	—	ns	N = prescale value (1, 4, 16)

Note 1: These parameters are characterized but not tested in manufacturing.

FIGURE 25-7: OUTPUT COMPARE MODULE (OC1) TIMING CHARACTERISTICS



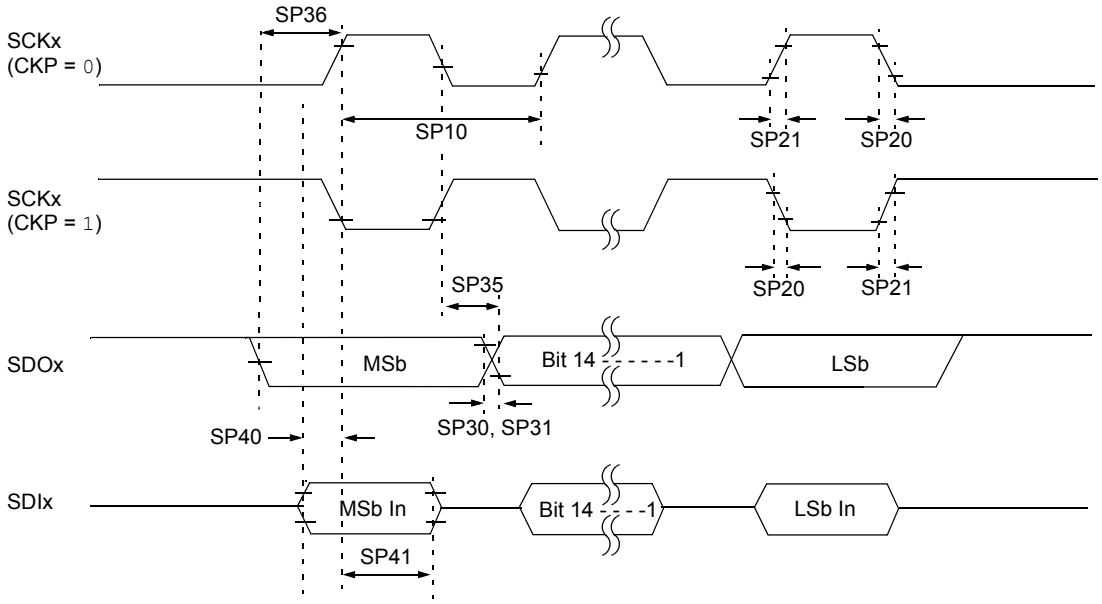
Note: Refer to Figure 25-1 for load conditions.

TABLE 25-26: OUTPUT COMPARE MODULE TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param.	**Symbol**	**Characteristic(1)**	**Min.**	**Typ.**	**Max.**	**Units**	**Conditions**
OC10	TccF	OC1 Output Fall Time	—	—	—	ns	See Parameter DO32
OC11	TccR	OC1 Output Rise Time	—	—	—	ns	See Parameter DO31

Note 1: These parameters are characterized but not tested in manufacturing.

FIGURE 25-13: SPIx MASTER MODE (FULL-DUPLEX, CKE = 1, CKP = x, SMP = 1) TIMING CHARACTERISTICS



Note: Refer to Figure 25-1 for load conditions.

TABLE 25-31: SPIx MASTER MODE (FULL-DUPLEX, CKE = 1, CKP = x, SMP = 1) TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Symbol**	**Characteristic(1)**	**Min**	**Typ(2)**	**Max**	**Units**	**Conditions**
SP10	TscP	Maximum SCKx Frequency	—	—	9	MHz	See **Note 3**
SP20	TscF	SCKx Output Fall Time	—	—	—	ns	See Parameter DO32 and **Note 4**
SP21	TscR	SCKx Output Rise Time	—	—	—	ns	See Parameter DO31 and **Note 4**
SP30	TdoF	SDOx Data Output Fall Time	—	—	—	ns	See Parameter DO32 and **Note 4**
SP31	TdoR	SDOx Data Output Rise Time	—	—	—	ns	See Parameter DO31 and **Note 4**
SP35	TscH2doV, TscL2doV	SDOx Data Output Valid after SCKx Edge	—	6	20	ns	
SP36	TdoV2sc, TdoV2scL	SDOx Data Output Setup to First SCKx Edge	30	—	—	ns	
SP40	TdiV2scH, TdiV2scL	Setup Time of SDIx Data Input to SCKx Edge	30	—	—	ns	
SP41	TscH2diL, TscL2diL	Hold Time of SDIx Data Input to SCKx Edge	30	—	—	ns	

Note 1: These parameters are characterized, but are not tested in manufacturing.

2: Data in "Typ" column is at 3.3V, 25°C unless otherwise stated.

3: The minimum clock period for SCKx is 111 ns. The clock generated in master mode must not violate this specification.

4: Assumes 50 pF load on all SPIx pins.

TABLE 25-41: HIGH-SPEED ANALOG COMPARATOR MODULE SPECIFICATIONS

DC CHARACTERISTICS[2]			Standard Operating Conditions (unless otherwise stated) Operating temperature: -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param.	**Symbol**	**Characteristic**	**Min.**	**Typ.**	**Max.**	**Units**	**Comments**
CM10	VIOFF	Input Offset Voltage	-58	+14/-40	66	mV	
CM11	VICM	Input Common-Mode Voltage Range[1]	0	—	AVDD	V	
CM14	TRESP	Large Signal Response	21	30	49	ns	V+ input step of 100 mv while V- input held at AVDD/2. Delay measured from analog input pin to PWM output pin.

Note 1: These parameters are for design guidance only and are not tested in manufacturing.

2: Overall functional device operation at VBORMIN < VDD < VDDMIN is tested, but not characterized. All device analog modules, such as the ADC, etc., will function but with degraded performance below VDDMIN. Refer to Parameter BO10 in Table 25-11 for BOR values.

TABLE 25-42: DAC MODULE SPECIFICATIONS

AC and DC CHARACTERISTICS[2]			Standard Operating Conditions (unless otherwise stated) Operating temperature: -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param.	**Symbol**	**Characteristic**	**Min.**	**Typ.**	**Max.**	**Units**	**Comments**
DA01	EXTREF	External Voltage Reference[1]	0	—	AVDD – 1.6	V	
DA08	INTREF	Internal Voltage Reference[1]	1.15	1.25	1.35	V	
DA02	CVRES	Resolution		10		Bits	
DA03	INL	Integral Nonlinearity Error	-7	-1	+7	LSB	AVDD = 3.3V, DACREF = (AVDD/2)V
DA04	DNL	Differential Nonlinearity Error	-5	-0.5	+5	LSB	
DA05	EOFF	Offset Error	0.4	-0.8	2.6	%	
DA06	EG	Gain Error	0.4	-1.8	5.2	%	
DA07	TSET	Settling Time[1]	711	1551	2100	ns	Measured when RANGE = 1 (high range) and the CMREF<9:0> bits transition from 0x1FF to 0x300

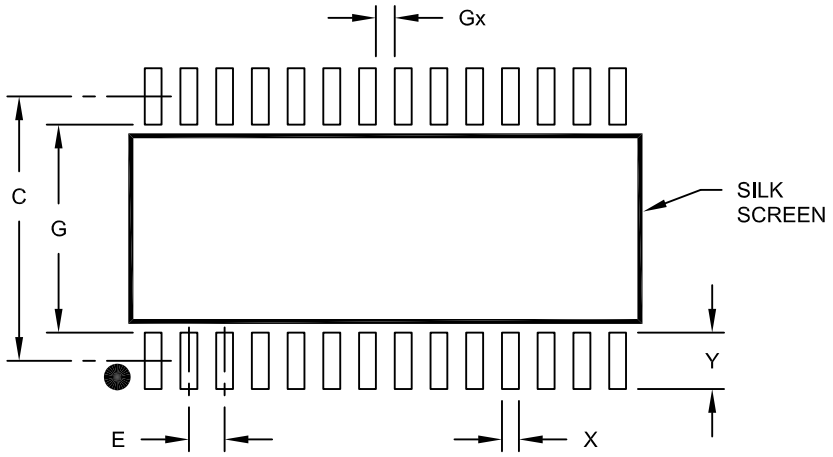
Note 1: Parameters are for design guidance only and are not tested in manufacturing.

2: Overall functional device operation at VBORMIN < VDD < VDDMIN is tested but not characterized. All device analog modules such as the ADC, etc., will function but with degraded performance below VDDMIN. Refer to Parameter BO10 in Table 25-11 for BOR values.

NOTES:

28-Lead Plastic Small Outline (SO) - Wide, 7.50 mm Body [SOIC]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



RECOMMENDED LAND PATTERN

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E		1.27 BSC	
Contact Pad Spacing	C		9.40	
Contact Pad Width (X28)	X			0.60
Contact Pad Length (X28)	Y			2.00
Distance Between Pads	Gx	0.67		
Distance Between Pads	G	7.40		

Notes:

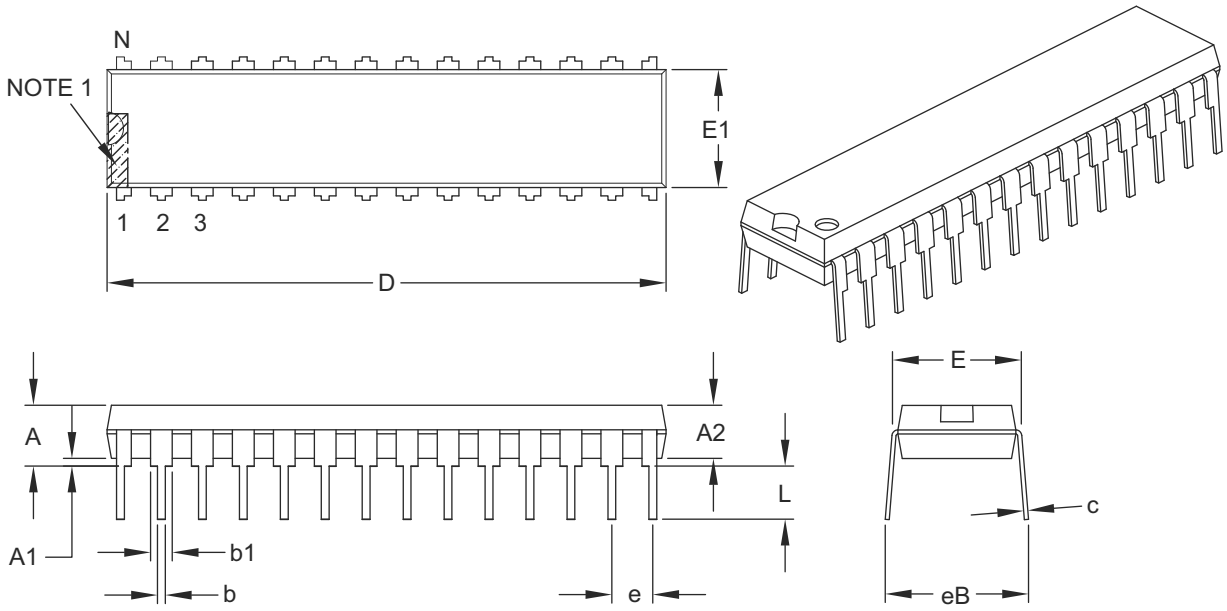
1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2052A

28-Lead Skinny Plastic Dual In-Line (SP) – 300 mil Body [SPDIP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		INCHES		
Dimension Limits		MIN	NOM	MAX
Number of Pins	N		28	
Pitch	e		.100 BSC	
Top to Seating Plane	A	–	–	.200
Molded Package Thickness	A2	.120	.135	.150
Base to Seating Plane	A1	.015	–	–
Shoulder to Shoulder Width	E	.290	.310	.335
Molded Package Width	E1	.240	.285	.295
Overall Length	D	1.345	1.365	1.400
Tip to Seating Plane	L	.110	.130	.150
Lead Thickness	c	.008	.010	.015
Upper Lead Width	b1	.040	.050	.070
Lower Lead Width	b	.014	.018	.022
Overall Row Spacing §	eB	–	–	.430

Notes:

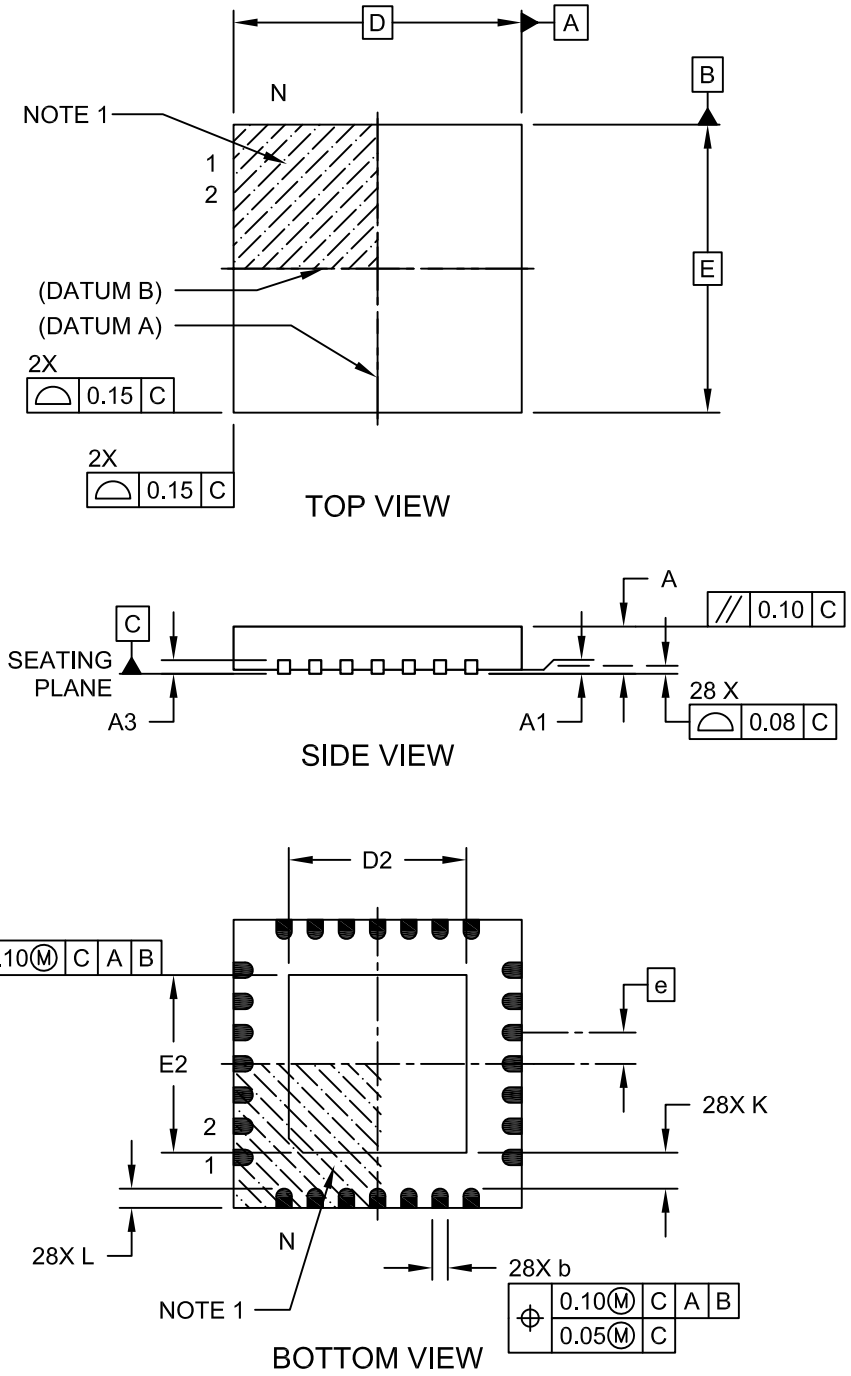
1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. § Significant Characteristic.
3. Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010" per side.
4. Dimensioning and tolerancing per ASME Y14.5M.

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing C04-070B

28-Lead Plastic Quad Flat, No Lead Package (MM) - 6x6x0.9mm Body [QFN-S]
With 0.40 mm Terminal Length

Note:	For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Microchip Technology Drawing C04-124C Sheet 1 of 2